

ABSTRACT

Ag ALLOY FILM AND SPUTTERING TARGET FOR FORMING Ag ALLOY FILM

5 This Ag alloy film includes: In: 0.1% by mass to 1.5% by mass; and Cu: 1 ppm
by mass to 50 ppm by mass, with the remainder being Ag and inevitable impurities. This
sputtering target includes: In: 0.1% by mass to 1.5% by mass; and Cu: 1 ppm by mass to
50 ppm by mass, with the remainder being Ag and inevitable impurities, in which an
oxygen concentration is less than 50 ppm by mass, an area of a sputtering surface is 0.25
10 m² or more, and an in-plane Cu concentration distribution $D_{Cu} (= (\sigma_{Cu}/\mu_{Cu}) \times 100)$ is 40% or
less.

FIG. 1